
PRODUCT CHANGE NOTICE

**Manufacturing Site Change for
Assembly of Intersil Product
ISL58797CRTZ-T13**

**Refer to:
PCN13001B**

Date: April 28, 2014

April 28, 2014

To: Our Valued Intersil Customer

Subject: **Manufacturing Site Change for Assembly of Intersil Product ISL58797CRTZ-T13 –
STATS ChipPAC (SCM) - Kuala Lumpur, Malaysia**

PCN13001B is being issued to inform customers that Intersil has withdrawn notice PCN13001 that was issued on January 09, 2013. The implementation of the manufacturing site change as outlined in the notice has been canceled. The contents of the original notice, PCN13001, are included below for reference.

This notice is to inform you that Intersil is transitioning assembly operations to the STATS ChipPAC (SCM) facility for the ISL58797CRTZ-T13 product. Intersil will discontinue the use of the current facility, Unisem, upon expiration of the ninety day period outlined in this notice. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. As of this notice, all product and package specific qualification activities are complete.

The STATS ChipPAC Malaysia (SCM) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and currently qualified as a primary supplier to Intersil for assembly of QFN packaged products. There will be no change in the package outline drawing (POD) or moisture sensitivity level (MSL).

The assembly qualification plan is designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. The reliability summary is included for reference. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, shipment, etc.) will continue to be processed to previously established conditions and systems.

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at SCM may also be identified by the assembly site code (country of assembly) when marked on the devices. The site code for product assembled at SCM is "H".

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product assembled at SCM facility beginning *ninety* days from the date of this notification or upon depletion of existing inventory.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,



Jeff Touvell
Intersil Corporation

PCN13001B

CC: J. Touvell B. Lee D. Nguyen S. Aji D. DeCrosta

PCN13001 – Reliability Summary

Legend					
Fail	Warning	Pass	QBE	Waived	NA

Reliability Test	ISL58797-SCM Plan Rel: 2012-12-21	Comments
High Temperature Operating Life	SRN120013 Rev 0 0/79 125C 1000hr completed 2012-03-21 disposition=A SRN120013 Rev 1 0/80 125C 1000hr completed 2012-03-21 disposition=A	ISL58797-SCM: QBE: Qualified by extension of ISL58791V(28pin version of ISL58796)
Moisture Sensitivity Classification	MRT12158 MSL=1@260C (Pb Free) Approved=Yes	
Unbiased HAST	SRN100280 Rev 0 0/78 130C, 85%RH PRECOND L1 PBFREE 96hr completed 2010-10-27 disposition=A	
Destructive Wire Pull after HAST	QFN is a prominent & well qualified package at SCM. Waived by Reliability Engineering	
Temperature Cycle	SRN100280 Rev 0 0/78 -40C TO 125C PRECOND L1 PBFREE 1000cy completed 2010-12-01 disposition=A	
Destructive Wire Pull after Temp Cycle	QFN is a prominent & well qualified package at SCM. Waived by Reliability Engineering	